Solder paste NP303-WS7157-T7

Product description

GENMA solder paste – our NP303-WS7157-T7 solder paste with easy to clean water soluble flux. It convinces with its outstanding printability, highly precise contours and consistent adhesiveness in the pick-and-place process. Its extremely good wetting properties, produce perfect soldering joints. Hardly any voids in the solder connections. Cleaning of flux residues with water after soldering is required. The solder paste can be soldered under nitrogen reflow.

Technical properties

	Specific value	Testing method
Alloy	Sn 96,5 / Ag 3,0 / Cu 0,5 / SAC305	
Melting temperature range	217 - 221	IEC61189-11
Powder size (µm)	2 - 11, type 7	IPC-TM-650-2.2.14.2

Compliance

Dated 13.11.2025

Conform with RoHS-Regulation 2011/65/EU and 2015/863/EU.

Contains no substances (SVHC-list) more than threshold (0,1%) according to REACH legislation EG Nr. 1907/2006.

Contains no substances as defined by the Toxic Substance Control Act (TSCA) of the United States Environmental Protection Agency.

Contains no substances according to POP Regulation EU 2019/1021.

Contains no Per- and PolyFuluoroAlkyl Substances (PFAS).

Contains no phthalates or latex.

Contains no substances according to California Proposition 65.

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